Octal 3-State Inverting Transciever

The MC74ACT640 octal bus transceiver is designed for asynchronous two-way communication between data buses. The device transmits data from bus \overline{A} to bus B when $T/\overline{R} = HIGH$, or from bus \overline{B} to bus A when $T/\overline{R} = LOW$. The enable input can be used to disable the device so the buses are effectively isolated.

Features

- Bidirectional Data Path
- A and B Outputs Sink 24 mA/Source -24 mA
- TTL Compatible Inputs
- Pb-Free Packages are Available*

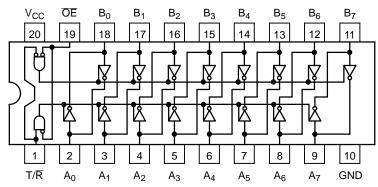


Figure 1. Pinout: 20-Lead Packages Conductors
(Top View)

PIN ASSIGNMENT

| PIN | FUNCTION | |
|--------------------------------|----------------------------------|--|
| A ₀ -A ₇ | Side A Inputs or 3-State Outputs | |
| ŌĒ | Output Enable Input | |
| T/R | Transmit/Receive Input | |
| B ₀ -B ₇ | Side B Inputs or 3-State Outputs | |

TRUTH TABLE

| OE | T/R | Applied Inputs | Valid Direction I/P→O/P | Output |
|----|-----|-------------------|-------------------------------|--------|
| Н | Х | Х | Х | Х |
| L | Н | Н | Ā to B | L |
| L | Н | L | Ā to B | Н |
| L | L | Н | B to A | L |
| L | L | L | B to A | Н |

H = HIGH Voltage Level L = LOW Voltage Level

X = Immaterial



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PDIP-20 N SUFFIX CASE 738



SOIC-20W DW SUFFIX CASE 751D



SOEIAJ-20 M SUFFIX CASE 967

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|-----------------|------------------------|-----------------------|
| MC74ACT640N | PDIP-20 | 18 Units/Rail |
| MC74ACT640NG | PDIP-20 (Pb-Free) | 18 Units/Rail |
| MC74ACT640DW | SOIC-20 | 38 Units/Rail |
| MC74ACT640DWG | SOIC-20 (Pb-Free) | 38 Units/Rail |
| MC74ACT640DWR2 | SOIC-20 | 1000 / Tape & Reel |
| MC74ACT640DWR2G | SOIC-20 (Pb-Free) | 1000 / Tape & Reel |
| MC74ACT640MEL | SOEIAJ-20 | 2000 / Tape & Reel |
| MC74ACT640MELG | SOEIAJ-20 (Pb-Free) | 2000 / Tape & Reel |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

DEVICE MARKING INFORMATION

See general marking information in the device marking section on page 4 of this data sheet.

^{*}For additional information on our Pb–Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

MAXIMUM RATINGS

| Symbol | Paramet | er | Value | Unit |
|----------------------|---|--|---|------|
| V _{CC} | DC Supply Voltage | | -0.5 to +7.0 | V |
| VI | DC Input Voltage | | $-0.5 \le V_{\text{I}} \le V_{\text{CC}} + 0.5$ | V |
| Vo | DC Output Voltage | (Note 1) | $-0.5 \le V_{O} \le V_{CC} + 0.5$ | V |
| I _{IK} | DC Input Diode Current | | ±20 | mA |
| lok | DC Output Diode Current | | ±50 | mA |
| I _O | DC Output Sink/Source Current | | ±50 | mA |
| I _{CC} | DC Supply Current per Output Pin | | ±50 | mA |
| I _{GND} | DC Ground Current per Output Pin | | ±50 | mA |
| T _{STG} | Storage Temperature Range | | -65 to +150 | °C |
| TL | Lead temperature, 1 mm from Case for 10 | Seconds | 260 | °C |
| TJ | Junction temperature under Bias | | +150 | °C |
| θ_{JA} | Thermal resistance | PDIP SOIC | 67 96 | °C/W |
| P_{D} | Power Dissipation in Still Air at 85°C | PDIP SOIC | 750 500 | mW |
| MSL | Moisture Sensitivity | | Level 1 | |
| F _R | Flammability Rating | Oxygen Index: 30% – 35% | UL 94 V-0 @ 0.125 in | |
| V _{ESD} | ESD Withstand Voltage | Human Body Model (Note 2) Machine Model (Note 3) Charged Device Model (Note 4) | > 2000 > 200 > 1000 | V |
| I _{Latchup} | Latchup Performance Above V | CC and Below GND at 85°C (Note 5) | ±100 | mA |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

- 1. I_O absolute maximum rating must be observed.
- 2. Tested to EIA/JESD22-A114-A.
- 3. Tested to EIA/JESD22-A115-A.
- Tested to JESD22-C101-A.
- 5. Tested to EIA/JESD78.

RECOMMENDED OPERATING CONDITIONS

| Symbol | Parameter | Min | Тур | Max | Unit |
|------------------------------------|---|------------|-----------|-----------------|------|
| V _{CC} | DC Input Voltage (Referenced to GND) | 4.5 | | 5.5 | V |
| V _{in} , V _{out} | DC Input Voltage, Output Voltage (Referenced to GND) | 0 | | V _{CC} | V |
| T _A | Operating Temperature, All Package Types | -40 | 25 | +85 | °C |
| t _r , t _f | Input Rise and Fall Time (Note 7) $ V_{CC} = 4.5 $ $ V_{CC} = 5.5 $ | V 0 V 0 | 10 8.0 | 10 8.0 | ns/V |
| T _J | Junction Temperature (PDIP) | | | 140 | °C |
| I _{OH} | Output Current – High | | | -24 | mA |
| I _{OL} | Output Current – Low | | | 24 | mA |

^{6.} Unused Inputs may not be left open. All inputs must be tied to a high voltage level or low logic voltage level.
7. V_{in} from 0.8 V to 2.0 V; refer to individual Data Sheets for devices that differ from the typical input rise and fall times.

DC CHARACTERISTICS

| | | V _{CC} | T _A = - | +25°C | T _A = -40°C to +85°C | | |
|--------------------------------------|--|-----------------|--------------------|-----------------------|------------------------------------|----------|--|
| Symbol | Parameter | (V) | Тур | Typ Guaranteed Limits | | Unit | Conditions |
| V _{IH} | Minimum High Level Input Voltage | 4.5 5.5 | 1.5 1.5 | 2.0 2.0 | 2.0 2.0 | V V | V _{OUT} = 0.1 V or V _{CC} - 0.1 V |
| V _{IL} | Maximum Low Level Input Voltage | 4.5 5.5 | 1.5 1.5 | 0.8 0.8 | 0.8 0.8 | V V | V _{OUT} = 0.1 V or V _{CC} - 0.1 V |
| V _{OH} | Minimum High Level Output Voltage | 4.5 5.5 | 4.49 5.49 | 4.4 5.4 | 4.4 5.4 | V V | I _{OUT} = -50 μA |
| | | 4.5 5.5 | | 3.86 4.86 | 3.76 4.76 | V V | * V _{IN} = V _{IL} or V _{IH} -24 mA $_{OH}$ -24 mA |
| V _{OL} | Maximum Low Level Output Voltage | 4.5 5.5 | 0.001 0.001 | 0.1 0.1 | 0.1 0.1 | V V | I _{OUT} = 50 μA |
| | | 4.5 5.5 | | 0.36 0.36 | 0.44 0.44 | V V | * V _{IN} = V _{IL} or V _{IH} -24 mA $_{OH}$ -24 mA |
| I _{IN} | Maximum Input Leakage Current | 5.5 | | ±0.1 | ±1.0 | μΑ | $V_I = V_{CC}$, GND |
| ΔI_{CCT} | Additional Max. I _{CC} /Input | 5.5 | 0.6 | | 1.5 | mA | V _I = V _{CC} – 2.1 V |
| I _{OZ} | Maximum 3–State Current | 5.5 | | ±0.5 | ±5.0 | μΑ | $ \begin{array}{c} V_{I} \; (OE) = V_{IL}, V_{IH} \\ V_{I} = V_{CC}, GND \\ V_{O} = V_{CC}, GND \end{array} $ |
| I _{OLD} I _{OHD} | †Minimum Dynamic Output Current | 5.5 5.5 | | | 75 –75 | mA mA | V _{OLD} = 1.65 V Max |
| I _{CC} | Maximum Quiescent Supply Current | 5.5 | | 8.0 | 80 | μΑ | V _{IN} = V _{CC} or GND |

^{*}All outputs loaded; thresholds on input associated with output under test. †Maximum test duration 2.0 ms, one output loaded at a time.

AC CHARACTERISTICS $t_r = t_f = 3.0$ ns (For Figures and Waveforms, See Figures 2 and 3.)

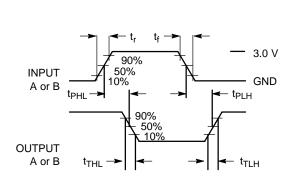
| | | | V _{CC} * | T _A = - | ⊦25°C 50 pF | T _A = -40°C C _L = 5 | C to +85°C 50 pF | |
|------------------|---------------------|-----------------------|-------------------|--------------------|----------------|--|---------------------|------|
| Symbol | Para | ameter | (V) | Min | Max | Min | Max | Unit |
| t _{PLH} | Propagation Delay | An to Bn or Bn to An | 5.0 | 1.5 | 8.0 | 1.0 | 8.5 | ns |
| t _{PHL} | Propagation Delay | An to Bn or Bn to An | 5.0 | 1.5 | 8.0 | 1.0 | 9.0 | ns |
| t _{PZH} | Output Enable Time | OE to An or Bn | 5.0 | 1.5 | 10.0 | 1.0 | 11.0 | ns |
| t _{PZL} | Output Enable Time | OE to An or Bn | 5.0 | 1.5 | 10.0 | 1.0 | 11.0 | ns |
| t _{PHZ} | Output Disable Time | T/R or OE to An or Bn | 5.0 | 1.5 | 10.0 | 1.0 | 11.0 | ns |
| t _{PLZ} | Output Disable Time | T/R or OE to An or Bn | 5.0 | 1.5 | 10.0 | 1.0 | 11.0 | ns |

^{*}Voltage Range 5.0 V is 5.0 V ±0.5 V

CAPACITANCE

| Symbol | Parameter | Value Typ | Unit | Test Conditions |
|------------------|-------------------------------|-----------|------|-------------------------|
| C _{IN} | Input Capacitance | 4.5 | pF | V _{CC} = 5.0 V |
| C _{I/O} | Input/Output Capacitance | 15 | pF | V _{CC} = 5.0 V |
| C _{PD} | Power Dissipation Capacitance | 45 | pF | V _{CC} = 5.0 V |

SWITCHING WAVEFORMS



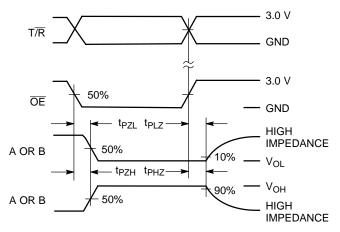
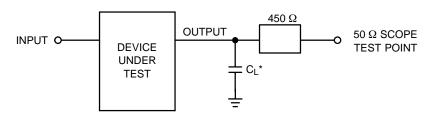


Figure 2.

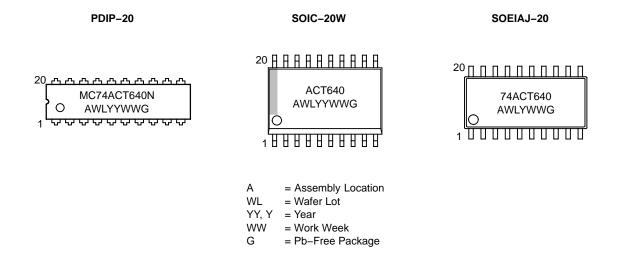
Figure 3.



*Includes all probe and jig capacitance

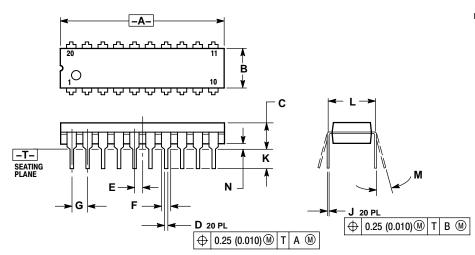
Figure 4. Test Circuit

MARKING DIAGRAMS



PACKAGE DIMENSIONS

PDIP-20 **N SUFFIX** PLASTIC DIP PACKAGE CASE 738-03 ISSUE E



- NOTES:

 1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.

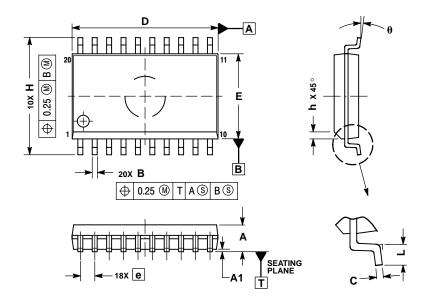
 2. CONTROLLING DIMENSION: INCH.

 3. DIMENSION L TO CENTER OF LEAD WHEN FORMED PARALLEL.

- DIMENSION B DOES NOT INCLUDE MOLD FLASH.

| | INC | HES | MILLIN | IETERS | |
|-----|-----------|-------|----------|--------|--|
| DIM | MIN | MAX | MIN | MAX | |
| Α | 1.010 | 1.070 | 25.66 | 27.17 | |
| В | 0.240 | 0.260 | 6.10 | 6.60 | |
| С | 0.150 | 0.180 | 3.81 | 4.57 | |
| D | 0.015 | 0.022 | 0.39 | 0.55 | |
| Е | 0.050 | BSC | 1.27 BSC | | |
| F | 0.050 | 0.070 | 1.27 | 1.77 | |
| G | 0.100 | BSC | 2.54 BSC | | |
| J | 0.008 | 0.015 | 0.21 | 0.38 | |
| K | 0.110 | 0.140 | 2.80 | 3.55 | |
| L | 0.300 BSC | | 7.62 | BSC | |
| M | 0° | 15° | 0° | 15° | |
| N | 0.020 | 0.040 | 0.51 | 1.01 | |

SOIC-20W **DW SUFFIX** CASE 751D-05 **ISSUE G**

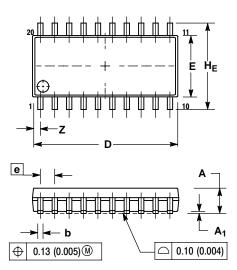


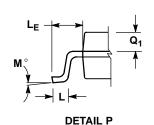
- NOTES:
 1. DIMENSIONS ARE IN MILLIMETERS.
 2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
 3. DIMENSIONS D AND E DO NOT INCLUDE MOLD PROTRUSION.
 4. MAXIMUM MOLD PROTRUSION 0.15 PER SIDE.
 5. DIMENSION B DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE PROTRUSION SHALL BE 0.13 TOTAL IN EXCESS OF B DIMENSION AT MAXIMUM MATERIAL CONDITION.

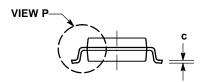
| | MILLIMETERS | | | | |
|-----|-------------|-------|--|--|--|
| DIM | MIN | MAX | | | |
| Α | 2.35 | 2.65 | | | |
| A1 | 0.10 | 0.25 | | | |
| В | 0.35 | 0.49 | | | |
| С | 0.23 | 0.32 | | | |
| D | 12.65 | 12.95 | | | |
| Е | 7.40 | 7.60 | | | |
| е | 1.27 | BSC | | | |
| Н | 10.05 | 10.55 | | | |
| h | 0.25 | 0.75 | | | |
| L | 0.50 | 0.90 | | | |
| θ | 0 ° | 7 ° | | | |

PACKAGE DIMENSIONS

SOEIAJ-20 **M SUFFIX** CASE 967-01 **ISSUE A**







NOTES:

- DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
- CONTROLLING DIMENSION: MILLIMETER
 DIMENSIONS D AND E DO NOT INCLUDE MOLD FLASH OR PROTRUSIONS AND ARE MEASURED AT THE PARTING LINE. MOLD FLASH OR PROTRUSIONS SHALL NOT EXCEED 0.15
- (0.006) PER SIDE.
 . TERMINAL NUMBERS ARE SHOWN FOR REFERENCE ONLY
- THE LEAD WIDTH DIMENSION (b) DOES NOT INCLUDE DAMBAR PROTRUSION. ALLOWABLE DAMBAR PROTRUSION SHALL BE 0.08 (0.003) TOTAL IN EXCESS OF THE LEAD WIDTH
 DIMENSION AT MAXIMUM MATERIAL CONDITION. DAMBAR CANNOT BE LOCATED ON THE LOWER RADIUS OR THE FOOT. MINIMUM SPACE BETWEEN PROTRUSIONS AND ADJACENT LEAD TO BE 0.46 (0.018).

| , , | | | | | |
|----------------|-------------|-------|-----------|-------|--|
| | MILLIMETERS | | INC | HES | |
| DIM | MIN | MAX | MIN | MAX | |
| Α | | 2.05 | | 0.081 | |
| A ₁ | 0.05 | 0.20 | 0.002 | 0.008 | |
| b | 0.35 | 0.50 | 0.014 | 0.020 | |
| С | 0.15 | 0.25 | 0.006 | 0.010 | |
| D | 12.35 | 12.80 | 0.486 | 0.504 | |
| Е | 5.10 | 5.45 | 0.201 | 0.215 | |
| е | 1.27 | BSC | 0.050 BSC | | |
| HE | 7.40 | 8.20 | 0.291 | 0.323 | |
| L | 0.50 | 0.85 | 0.020 | 0.033 | |
| LE | 1.10 | 1.50 | 0.043 | 0.059 | |
| М | 0 ° | 10° | 0° | 10° | |
| Q ₁ | 0.70 | 0.90 | 0.028 | 0.035 | |
| Z | | 0.81 | | 0.032 | |

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